8-1734508-0 ACTIVE

AMPMODU | AMPMODU 2 mm

TE Internal #: 8-1734508-0

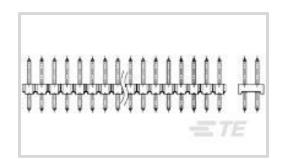
PCB Mount Header, Vertical, Board-to-Board, 80 Position, 2 mm [. 079 in] Centerline, Unshrouded, Gold, Through Hole - Solder,

Signal, AMPMODU 2 mm

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 80

Number of Rows: 2

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Header |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Header Type | Unshrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| PCB Mount Orientation | Vertical |
| Number of Positions | 80 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| Dielectric Withstanding Voltage (Max) | 650 VAC | |
|---------------------------------------|---------|--|
| Operating Voltage | 250 VAC | |

Body Features

Contact Features

| Contact Mating Area Length | 4 mm[.158 in] |
|----------------------------|---------------|
| 3 | |



| Mating Square Post Dimension | .5 mm[.02 in] |
|---------------------------------------------------------|----------------------------|
| PCB Contact Termination Area Plating Material Thickness | 2.54 µm |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Shape & Form | Square |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Brass |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .254 μm[10 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 1 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .5 mm[.02 in] |
| Termination Post & Tail Length | 2.6 mm[.102 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | 2 mm[.079 in] |
| Housing Material | Thermoplastic |
| Dimensions | |
| Row-to-Row Spacing | 2 mm[.079 in] |
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |
| Usage Conditions | |
| Operating Temperature Range | -40 - 105 °C[-40 - 221 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |



Packaging Features

| Packaging Type | Loose Piece |
|----------------------------|-------------|
| Other | |
| Position Locations Omitted | 0 |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|-----------------------------------------------|--------------------------------------------------------------------------------------------------------------------------|
| EU ELV Directive 2000/53/EC | Not Yet Reviewed |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUL 2021 (219) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Wave solder capable to 265°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Also in the Series | AMPMODU 2 mm





PCB Headers & Receptacles(8492)



Wire-to-Board Connector Assemblies & Housings(202)



Wire-to-Board Connector Contacts(27)

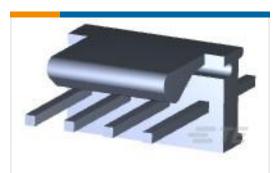
Customers Also Bought



TE Part #3-647166-4 4P MTA100 HDR ASSY,SM,FL,LF



TE Part #1-1393258-5 V23047-A1024-A501



TE Part #640456-4
04P MTA100 HDR ASSY F/L SQ STR



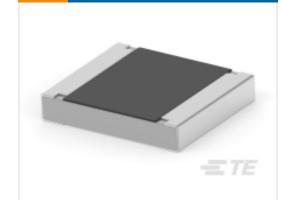
TE Part #796740-3
3 POS PCB MT 6.35MM HI CRT TBK



TE Part #1571983-4
GDH04S04=DIP SWITCH



TE Part #796740-2 2 POS PCB MT 6.35MM HI CRT TBK



TE Part #1-2176346-6 CRGCQ 1210 330R 5%



TE Part #3-643813-2 02P MTA100 CONN ASSY POL RIB



Documents

Product Drawings

AMPMODU,2.0MM, HDR, VRT MT, 8u" AU, 80P

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_8-1734508-0_C.2d_dxf.zip



English

Customer View Model

ENG_CVM_CVM_8-1734508-0_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_8-1734508-0_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Product Specifications

Product Specification

English